

Docket No.: 085027-0031

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 89518
: :
Jin-Yuan Lee : Confirmation Number: 3369
: :
Application No.: 09/684,519 : Group Art Unit: 2841
: :
Patent No.: 6,809,935 : Issued: October 26, 2004
: :
For: THERMALLY COMPLIANT PCB SUBSTRATE FOR THE APPLICATION OF CHIP
SCALE PACKAGES

TRANSMITTAL OF POWER OF ATTORNEY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF ELECTRONIC TRANSMISSION

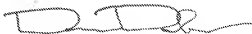
I hereby certify that this correspondence is being electronically transmitted to the
United States Patent and Trademark Office on March 11, 2011.
Patricia A. Balero
Patricia A. Balero

Sir:

Transmitted herewith is a Fee Address Indication Form, Power Of Attorney to Prosecute
Applications Before the USPTO, together with a Statement Under 37 CFR 3.73(b), which
revokes all previous powers of attorney given in the above-identified application and associates
the application with Customer Number 89518.

Respectfully submitted,

McDERMOTT WILL & EMERY LLP



Dennis A. Duchene
Registration No. 40,595

11682 El Camino Real, Suite 400
San Diego, CA 92130
Phone: 858.720.3300
Facsimile: 858.720.7800
Date: March 11, 2011

**Please recognize our Customer No. 89518
as our correspondence address.**